

4.0x4.0mm RIGHT ANGLE SURFACE MOUNT **LED LAMP**

Part Number: AA4040YS Yellow

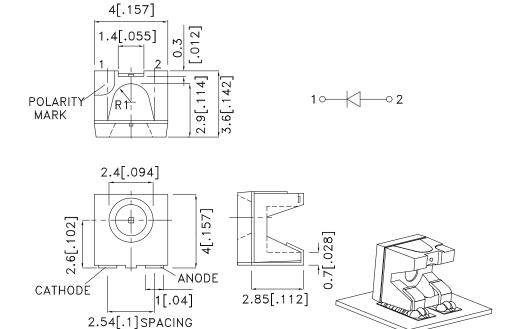
Features

- Single color.
- Suitable for all SMT assembly and solder process.
- Available on tape and reel.
- Ideal for backlighting.
- Package : 500pcs / reel.
- Moisture sensitivity level : level 3.
- RoHS compliant.

Description

The Yellow source color devices are made with Gallium Arsenide Phosphide on Gallium Phosphide Yellow Light Emitting Diode.

Package Dimensions





- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is $\pm 0.25(0.01")$ unless otherwise noted.
- The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
 The device has a single mounting surface. The device must be mounted according to the specifications.

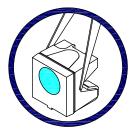
SPEC NO: DSAL0976 **REV NO: V.4B DATE: MAR/13/2013** PAGE: 1 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.Cui ERP: 1201006779

Handling Precautions

Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force.

As a result, special handling precautions need to be observed during assembly using silicone encapsulated LED products. Failure to comply might lead to damage and premature failure of the LED.

1. Handle the component along the side surfaces by using forceps or appropriate tools.



2. Do not directly touch or handle the silicone lens surface. It may damage the internal circuitry.





3. As silicone encapsulation is permeable to gases, some corrosive substances such as H_2S might corrode silver plating of leadframe. Special care should be taken if an LED with silicone encapsulation is to be used near such substances.

All design applications should refer to Kingbright application notes available at http://www.KingbrightUSA.com/ApplicationNotes

SPEC NO: DSAL0976 REV NO: V.4B DATE: MAR/13/2013 PAGE: 2 OF 6

APPROVED: WYNEC CHECKED: Allen Liu DRAWN: F.Cui ERP: 1201006779

Selection Guide

Part No.	Dice	Lens Type	lv (mcd) [2] @ 20mA		Viewing Angle [1]
		,	Min.	Тур.	201/2
AA4040YS Yellow (GaAsP/GaP)		Water Clear	ear 8		120°

- 1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
- Luminous intensity/ luminous Flux: +/-15%.
 Luminous intensity value is traceable to the CIE127-2007 compliant national standards.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590		nm	IF=20mA
λD [1]	Dominant Wavelength	Yellow	588		nm	IF=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35		nm	I==20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	IF=20mA
IR	Reverse Current	Yellow		10	uA	V _R =5V

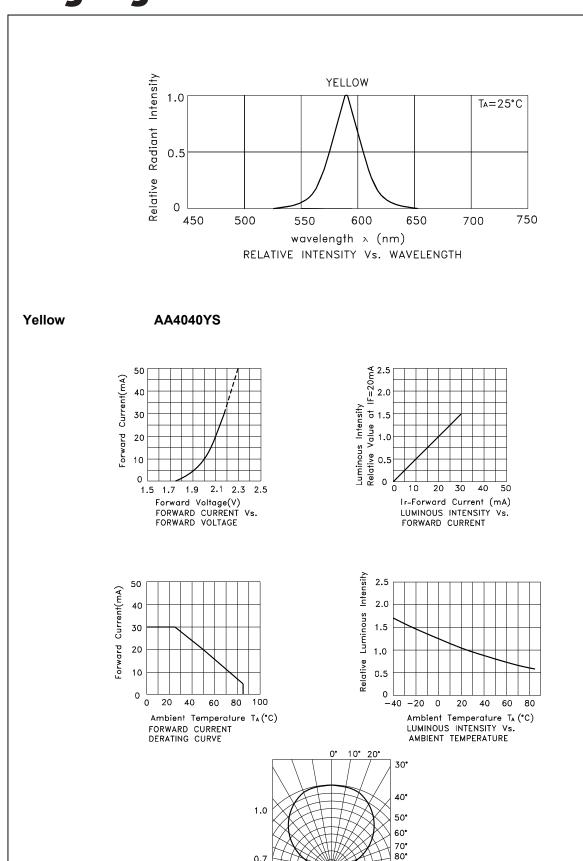
- 1.Wavelength: +/-1nm.
- Forward Voltage: +/-0.1V.
 Wavelength value is traceable to the CIE127-2007 compliant national standards.

Absolute Maximum Ratings at TA=25°C

Absolute maximum rutings at 1A 20 0					
Parameter	Yellow	Units			
Power dissipation	75	mW			
DC Forward Current	30	mA			
Peak Forward Current [1]	140	mA			
Reverse Voltage	5	V			
Operating Temperature	-40°C To +85°C				
Storage Temperature	-40°C To +85°C				

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

DATE: MAR/13/2013 SPEC NO: DSAL0976 **REV NO: V.4B** PAGE: 3 OF 6 APPROVED: WYNEC **CHECKED: Allen Liu** DRAWN: F.Cui ERP: 1201006779



SPEC NO: DSAL0976 APPROVED: WYNEC

REV NO: V.4B CHECKED: Allen Liu

0.7

DATE: MAR/13/2013 DRAWN: F.Cui

SPATIAL DISTRIBUTION

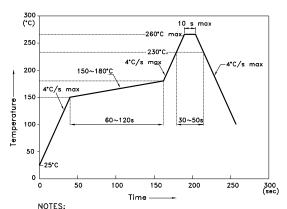
90°

PAGE: 4 OF 6 ERP: 1201006779

AA4040YS

Reflow soldering is recommended and the soldering profile is shown below. Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.



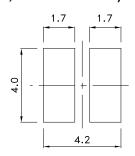
NOTES:

1.We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.

2.Don't cause stress to the epoxy resin while it is exposed to high temperature.

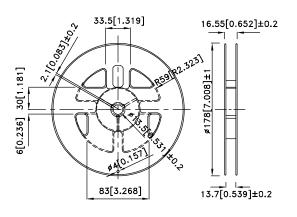
3.Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units: mm; Tolerance: ± 0.1)



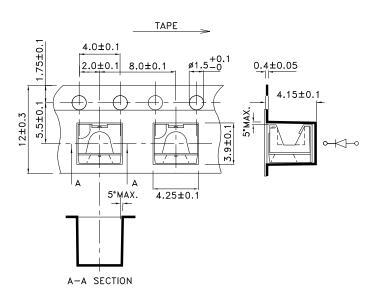
Tape Dimensions (Units: mm)

Reel Dimension

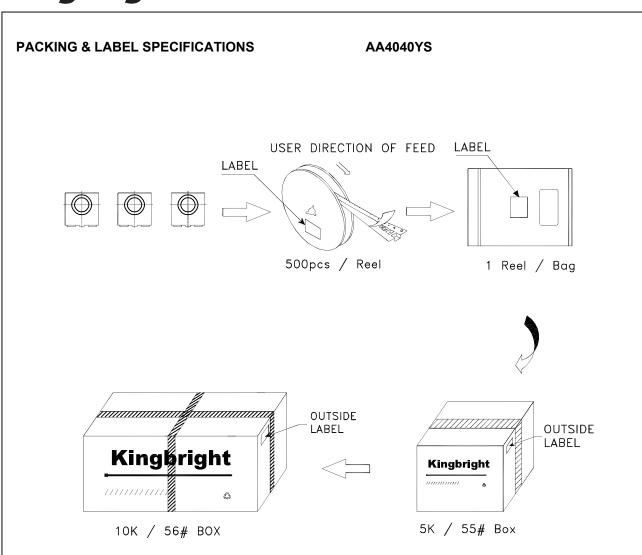


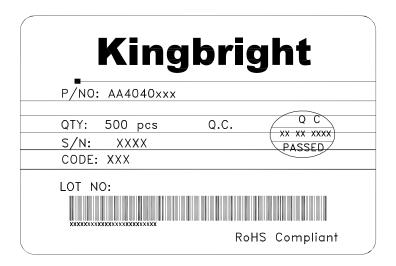
PAGE: 5 OF 6

ERP: 1201006779



SPEC NO: DSAL0976 **REV NO: V.4B DATE: MAR/13/2013 APPROVED: WYNEC CHECKED: Allen Liu** DRAWN: F.Cui





SPEC NO: DSAL0976 APPROVED: WYNEC REV NO: V.4B
CHECKED: Allen Liu

DATE: MAR/13/2013 DRAWN: F.Cui PAGE: 6 OF 6 ERP: 1201006779